

SKYPER®

Driver Core

Order Number L5063103 Datasheet valid for L5063103 Index 08

SKYPER 42 LJ R (coated)

Characteristics

t_{d(on.dia)}

t_{d(off,ana)}

t_{d(off,dig)}

RIN(err,prim)

CIN(err,prim)

Features*

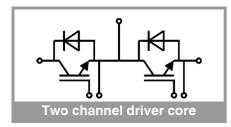
- Two output channels
- · Integrated power supply
- Separated failure/signal transmission ٠
- Selectable dead time
- Dynamic short-circuit detection ٠
- · SoftOff in error condition
- Active clamping
- · Selectable filter setting
- Multi failure management
- ROHS, UL recognized •
- Coated with SL1307

Typical Applications

• Driver for IGBT modules in bridge circuits in industrial application

Remarks

- · The insulation test is not performed as 100% series test at SEMIKRON
- The maximum DC-Link voltage is limited by the creepage and clearance distances; according to EN50178-1, PD II, OVC III
- · Operating temperature is real ambient temperature around the driver core
- Environmental conditions see **Technical Explanation**
- Do not touch the transformers



Absolute Maximum Ratings				
Symbol	Conditions	Values	Unit	
Vs	Supply voltage primary side	15.6	V	
V _{IH}	Input signal voltage (HIGH)	Vs + 0.3	V	
V _{IL}	Input signal voltage (LOW)	GND - 0.3	V	
I _{out(peak)}	Output peak current ¹⁾	24	А	
Iout(avg)	Output average current ¹⁾	120	mA	
f _{max}	Maximum switching frequency ²⁾	100	kHz	
V _{CE}	Collector emitter voltage ³⁾	1700	V	
V _{DC}	DC-Link voltage ⁴⁾	1200	V	
dv/dt	Rate of rise and fall of voltage secondary to primary side	100	kV/μs	
V _{isol}	Insulation test voltage ⁵⁾	4000	V	
Q _{out}	Output charge per pulse ⁶⁾	20	μC	
T _{op}	Operating temperature range	-40 85	°C	
T _{stg}	Storage temperature range	-40 85	°C	

Symbol Conditions min. max. Unit typ. Vs 15.6 Supply voltage primary side 144 15 Primary side undervoltage-lockout V_{UVLO(prim)} 12.2 shutdown threshold Primary side undervoltage-lockout 13.9 reset threshold Secondary side undervoltage-lockout shutdown threshold, positive gate 9.4 VUVLO(secP) voltage Secondary side undervoltage-lockout 13.3 reset threshold, positive gate voltage Secondary side undervoltage-lockout shutdown threshold, negative gate -4.1 V_{UVLO(secN)} voltage Secondary side undervoltage-lockout -5.8 reset threshold, negative gate voltage Supply current primary side (no load) 65 mA I_{S(idle)} Supply current primary side (full load) 700 mΑ I_{S(max)} VI Input signal voltage on/off Vs/0 VIT+ Input threshold voltage (HIGH) 8.6 VIT-Input threshold voltage (LOW) 6.7 Input resistance (switching signals) 33 kΩ RIN(sw) Input capacitance (switching signals) 0.01 CIN(sw) nF Turn-on output voltage 14.8 V_{G(on)} V_{G(off)} Turn-off output voltage -8 Turn-on propagation delay time 0.5 t_{d(on,ana)} μs for analog filter selection Turn-on propagation delay time

for digital filter selection Turn-off propagation delay time

for analog filter selection Turn-off propagation delay time

for digital filter selection Input resistance

(error input, primary side) Input capacitance

(error input, primary side)

V

V

V

V

v

V

v

V

v

v

v

٧

μs

μs

μs

kΩ

nF

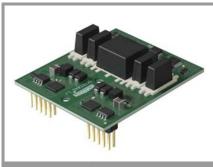
0.83

0.5

0.83

150

10



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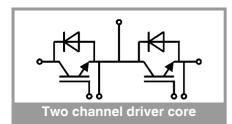
Typical Applications

 Driver for IGBT modules in bridge circuits in industrial application

Remarks

- The insulation test is not performed as 100% series test at SEMIKRON
- The maximum DC-Link voltage is limited by the creepage and clearance distances; according to EN50178-1, PD II, OVC III
- Operating temperature is real ambient temperature around the driver core
- Environmental conditions see Technical Explanation
- Do not touch the transformers

Characteristics					
Symbol	Conditions	min.	typ.	max.	Unit
R _{IN(err,sec)}	Input resistance (error inputs, secondary side)		150		kΩ
C _{IN(err,sec)}	Input capacitance (error inputs, secondary side)			0.01	nF
t _{d(err)}	Error propagation delay time ⁷⁾		0.7		μs
t _{d(err,ext)}	External error propagation delay time ⁸⁾		0.6		μs
t _{IDT}	Interlock dead time9)		2		μs
t _{jitter(ana)}	Signal transfer deviation for analog filter selection ¹⁰⁾		± 3		ns
t _{jitter(dig)}	Signal transfer deviation for digital filter selection ¹⁰⁾	± 12.5			ns
t _{SPS(ana)}	Short pulse suppression for analog filter selection	0.2			μs
t _{SPS(dig)}	Short pulse suppression for digital filter selection	0.39			μs
t _{POR}	Power-on reset time		0.15		S
t _{reset}	Error reset time ¹¹⁾	0.03			ms
V _{CE(ref)}	Reference voltage for V _{CE} -monitoring ¹²⁾			9	v
VITH(clamp)	Input threshold voltage clamping (HIGH) ¹³⁾			13	V
V _{ITL(clamp)}	Input threshold voltage clamping (LOW) ¹³⁾	2			V
R _{IN(clamp)}	Input resistance (clamping inputs)		150		kΩ
C _{IN(clamp)}	Input capacitance (clamping inputs)			0.01	nF
I _{clear(PS)}	Shortest distance in air, primary side to secondary side	12.2			mm
I _{clear(SS)}	Shortest distance in air, secondary sides	6.1			mm
I _{creep(PS)}	Shortest distance along the surface, primary side to secondary side (CTI > 175)	12.2			mm
I _{creep(SS)}	Shortest distance along the surface, secondary sides (CTI > 175)	6.1			mm
V _{imp}	Impulse withstand voltage ¹⁴⁾	8000			V
V _{PDPS}	Partial discharge extinction voltage, primary side to secondary side ¹⁵⁾	2107		V	
w	Weight		22		g
MTBF	Mean Time Between Failure ¹⁶⁾		7.5		10 ⁶ ł



Footnotes

Footnote	Description		
1)	The rated peak and average output current are valid over the full operating temperature range.		
2)	The rated maximum switching frequency is valid over the full operating temperature range.		
3)	Repetitive peak voltage across the semiconductor power rails.		
4)	The maximum DC-Link voltage is limited by creepage and clearance distances (according to EN50178-1, PD II, OVC III).		
5)	Test Conditions: ACrms, 2s, input to output.		
6)	If using power semiconductor modules with gate charges >2.5µC, the buffer capacitance of the driver's secondary sides and primary side has to be adjusted according to the corresponding Technical Explanation.		
7)	Time between the driver detects an error at the secondary side until the primary side reports an error at the interface.		
8)	Time between the driver receives an external error signal at the primary side until the driver turns off its outputs at the secondary side.		
9)	The interlock dead time prevents the two outputs from being activated simultaneously. The dead time generation starts with each turn-off command at the driver's primary side. The interlock dead time generation could be deactivated via pin 'CFG_IDT'.		
10)	The jitter is defined as the maximum deviation of the switching signal propagation delay time at constant environmental conditions. The signal transfer deviation t _{jitter(ana)} is valid if analog filtering is selected via pin 'CFG_FLT' and the interlock dead time, generated by the controller, is longer than the interlock dead time which is ensured by the driver itself.		
11)	Minimum time for which the driver is in error state.		
12)	The driver detects a desaturation event, when one of its outputs is in on-state and the applied voltage at the corresponding V _{CE} -monitoring input (pin 'VCE_IN') exceeds the reference voltage for V _{CE} -monitoring. As long as the blanking time has not been elapsed, the desaturation detection is deactivated. The blanking time is adjustable via the 'CFG_VCE' pin.		
13)	The driver's output switches to high-resistance state, when the output is in off-state and the applied voltage at the corresponding 'CLMP_IN' pin exceeds the input threshold voltage V _{ITH(clamp)} . The output returns to off-state when the applied voltage at pin 'CLMP_IN' falls below the input threshold voltage V _{ITL(clamp)} .		
14)	Test condition: 8000V, pulse according to EN50178-1.		
15)	The partial discharge extinction voltage in this data sheet is defined as peak voltage.		
16)	Conditions: $T_{op} = 40^{\circ}$ C; full load. Theoretical consideration according to SN 29500.		
17)	All external circuits, except the V _{CE} reference voltage adjustment, have to be supplied via pin 'PWR_VS_P_OUT' with respect to pin 'PWR_VS_N_OUT'. The rated average output current is reduced by the supply current of these external circuits.		

Pin description - primary side

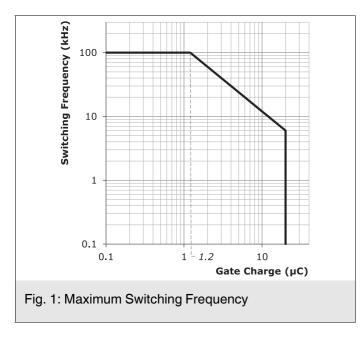
PIN	Signal	Function	Specifications
X10:01	PWR_GND	Ground potential for power supply and digital signals	To be connected to ground
X10:02	CFG_IDT	Interlock dead time configuration	15V logic; 150kΩ (pull-up) LOW = 2µs interlock dead time HIGH = No interlock dead time
X10:03	nERR_OUT	Error output	Open collector output; max. 18V/15mA (external pull-up resistor needed) LOW = Error HIGH = No error
X10:04	nERR_IN	Error input	15V logic inverted; 150kΩ/10nF (pull-up) LOW = External error HIGH = No external error
X10:05	CFG_ERR	Error behavior configuration in case of secondary side error	15V logic; 150kΩ (pull-down) LOW = Both outputs switch off HIGH = Outputs switch off with next turn-off signal at the corresponding input
X10:06	CFG_FLT	Filter configuration for switching signals	15V logic; 150kΩ (pull-down) LOW = Analog filter ($t_{SPS(ana)}$) HIGH = Digital filter ($t_{SPS(dig)}$)
X10:07	TOP_IN	Switching signal input (TOP)	15V logic; 33kΩ/0.01nF (pull-down) LOW = TOP switch off HIGH = TOP switch on
X10:08	BOT_IN	Switching signal input (BOT)	15V logic; 33kΩ/0.01nF (pull-down) LOW = BOT switch off HIGH = BOT switch on
X10:09	PWR_VS	Driver power supply	Stabilized +15V ±4%
X10:10	PWR_VS	Driver power supply	Stabilized +15V ±4%

Pin description - secondary side - TOP

PIN	Signal	Function	Specifications
X100:01	CFG_VCE	V _{CE} -monitoring reference voltage	External voltage divider needed
X100:02	VCE_IN	V _{CE} -monitoring input	External blocking diode needed
X100:03	PWR_VS_P_OUT	Power supply output, positive voltage	Equal to $V_{G(on)}^{17)}$ (external buffer capacitors can be connected)
X100:04	nERR_IN	External error input	15V logic inverted; 150kΩ/0.01nF (pull-up) LOW = External error HIGH = No external error
X100:05	TOP_ON	On signal path to TOP semiconductor	$\begin{array}{l} \mbox{External gate resistor needed} \\ (\mbox{in consideration of } I_{\mbox{out}(\mbox{avg})}, I_{\mbox{out}(\mbox{peak})}, V_{\mbox{G}(\mbox{on})}) \end{array}$
X100:06	TOP_OFF	Off signal path to TOP semiconductor	$\begin{array}{l} \mbox{External gate resistor needed} \\ (\mbox{in consideration of -}I_{out(avg)}, -I_{out(peak)}, V_{G(off)}) \end{array}$
X100:07	CLMP_IN	V _{CE} -clamping input	150kΩ/0.01nF (pull-down) In case of activated TOP_OFF: LOW = TOP_OFF equal to $V_{G(off)}$ HIGH = TOP_OFF floating
X100:08	PWR_GND	Ground potential for power supply and digital signals	Reference potential for gate voltages (emitter/source of power semiconductor)
X100:09	TOP_SOFTOFF	SoftOff signal path to TOP semiconductor	External gate resistor needed
X100:10	PWR_VS_N_OUT	Power supply output, negative voltage	Equal to $V_{G(off)}^{17)}$ (external buffer capacitors can be connected)

PIN	Signal	Function	Specifications
X200:01	CFG_VCE	V _{CE} -monitoring reference voltage	External voltage divider needed
X200:02	VCE_IN	V _{CE} -monitoring input	External blocking diode needed
X200:03	PWR_VS_P_OUT	Power supply output, positive voltage	Equal to $V_{G(on)}^{17)}$ (external buffer capacitors can be connected)
X200:04	nERR_IN	External error input	15V logic inverted; 150kΩ/0.01nF (pull-up) LOW = External error HIGH = No external error
X200:05	BOT_ON	On signal path to BOT semiconductor	$\label{eq:constraint} \begin{array}{c} \mbox{External gate resistor needed} \\ \mbox{(in consideration of } I_{out(avg)}, \ I_{out(peak)}, \ V_{G(on)}) \end{array}$
X200:06	BOT_OFF	Off signal path to BOT semiconductor	External gate resistor needed (in consideration of -I _{out(avg)} , -I _{out(peak)} , V _{G(off)})
X200:07	CLMP_IN	V _{CE} -clamping input	150kΩ/0.01nF (pull-down) In case of activated BOT_OFF: LOW = BOT_OFF equal to $V_{G(off)}$ HIGH = BOT_OFF floating
X200:08	PWR_GND	Ground potential for power supply and digital signals	Reference potential for gate voltages (emitter/source of power semiconductor)
X200:09	BOT_SOFTOFF	SoftOff signal path to BOT semiconductor	External gate resistor needed
X200:10	PWR_VS_N_OUT	Power supply output, negative voltage	Equal to $V_{G(off)}^{17)}$ (external buffer capacitors can be connected)

Pin description - secondary side - BOT



This is an electrostatic discharge sensitive device (ESDS) due to international standard IEC 61340.

***IMPORTANT INFORMATION AND WARNINGS**

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